

Geneva, Switzerland - 25 January 2018

Name	Employer	Affiliation
Abbott, John	Corning Incorporated	Corning Incorporated
Abedy, Yossuf		Pulse Electronics
Agnes, Andrea	STMicroelectronics	STMicroelectronics
Anslow, Peter	Ciena Corporation	Ciena Corporation
Bains, Amrik	Cisco Systems, Inc.	Cisco Systems, Inc.
Booth, Brad	Microsoft Corporation	Microsoft Corporation
Braun, Ralf-Peter	Deutsche Telekom AG	Deutsche Telekom AG
Brown, Alan M	ADTRAN Inc.	ADTRAN Inc.
Brychta, Michal		Analog Devices Inc.
Butter, Adrian	GLOBALFOUNDRIES	GLOBALFOUNDRIES
Calvin, John	Vital Technical Marketing, Wilder	VTM, V-Prime, Wilder
Chang, Xin	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Choudhury, Golam	OFS	OFS
Dawe, Piers J G	Mellanox Technologies	Mellanox Technologies
den Besten, Gerrit		NXP Semiconductors
DeSanti, Claudio	Cisco Systems, Inc.	Google
Diminico, Christopher	M C Communications, LLC	Panduit Corp.
Donahue, Curtis	University of New Hampshire	UNH-IOL
Dudek, Michael	Cavium	Cavium
Effenberger, Frank	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Estes, David	Spirent Communications	Spirent Communications
Franchuk, Brian	Emerson Automation Solutions	Emerson Automation Solutions
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH
Gorshe, Steven Scott	Microsemi Corporation	Microsemi Corporation
Gottron, Jens	Siemens AG	Siemens AG
Graber, Steffen	Pepperl+Fuchs GmbH	Pepperl+Fuchs GmbH
Gustlin, Mark	Xilinx Inc	Xilinx
Hajduczenia, Marek	Charter Communications	Charter Communications
Healey, Adam	Broadcom Ltd.	Broadcom Ltd.
Hormmeyer, Bernd	Phoenix Contact	Phoenix Contact
Huszk, Gergely	Self	Kone
Jimenez, Andrew	Anixter Inc.	Anixter Inc.
Johnson, John	Broadcom Limited	Broadcom Limited
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Kappertz, Jannis		Endress+Hauser
Kolesar, Paul	CommScope	CommScope, Inc.
Kondo, Taiji	MegaChips Corporation	MegaChips Corporation
Krieger, Olaf	Volkswagen AG	Volkswagen AG
Kumada, Taketo	Yazaki Corporation	Yazaki Corporation
Lapak, Jeffrey	University of New Hampshire	University of New Hampshire
Laubach, Mark	Broadcom Limited	Broadcom Corporation

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Name	Employer	Affiliation
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lewis, David	Lumentum Inc.	Lumentum Inc.
Lewis, Jon	Dell EMC	Dell
Lingle, Robert	OFS	OFS
Maguire, Valerie	The Siemon Company	The Siemon Company
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
McCarthy, Mick	Analog Devices Inc.	Analog Devices Inc.
Mcclellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
McSorley, Gregory	Amphenol Corporation	Amphenol Corporation
Nakamoto, Edward	Spirent Communications	Spirent Communications
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Palkert, Thomas	EIC	Molex-Macom
Pandey, Sujan	NXP Semiconductors	NXP Semiconductors
RAN, ADEE	Intel Corporation	Intel Corporation
Remein, Duane	Futurewei Technologies	Huawei Technologies Co. Ltd
Sakai, Toshiaki	Socionext	socionext
Sommers, Scott	Molex Incorporated	Molex Incorporated
Sparrowhawk, Bryan	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Sprague, Edward	Infinera Corporation	Infinera Corporation
Stassar, Peter	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Swanson, Steven	Corning Incorporated	Corning Incorporated
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Tracy, Nathan	TE Connectivity	TE Connectivity
Trowbridge, Stephen	Nokia	Nokia
Umnov, Alexander	Corning Incorporated	Corning Incorporated
Walker, Dylan	Cisco Systems, Inc.	Cisco Systems, Inc.
Wechsler, Christoph	Audi AG	Audi AG
Wienckowski, Natalie	General Motors Company	General Motors Company
Withey, James	Fluke Corporation	Fluke Corporation
Wucher, Markus	Endress + Hauser Flowtec AG	Endress + Hauser
Young, James	CommScope, Inc.	CommScope
Zerna, Conrad	Fraunhofer IIS	Fraunhofer IIS
Zhuang, Yan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Zimmerman, George	CME Consulting	ADI, APL Group, Aquantia, BMW,
Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.